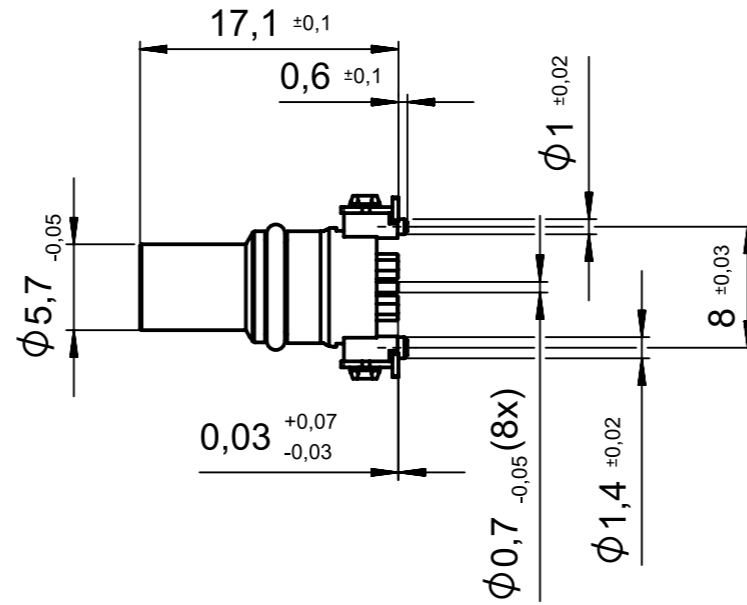
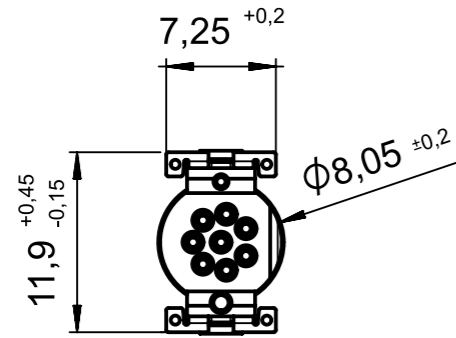
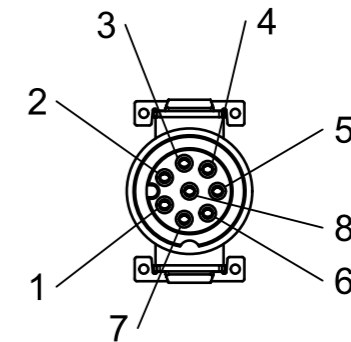


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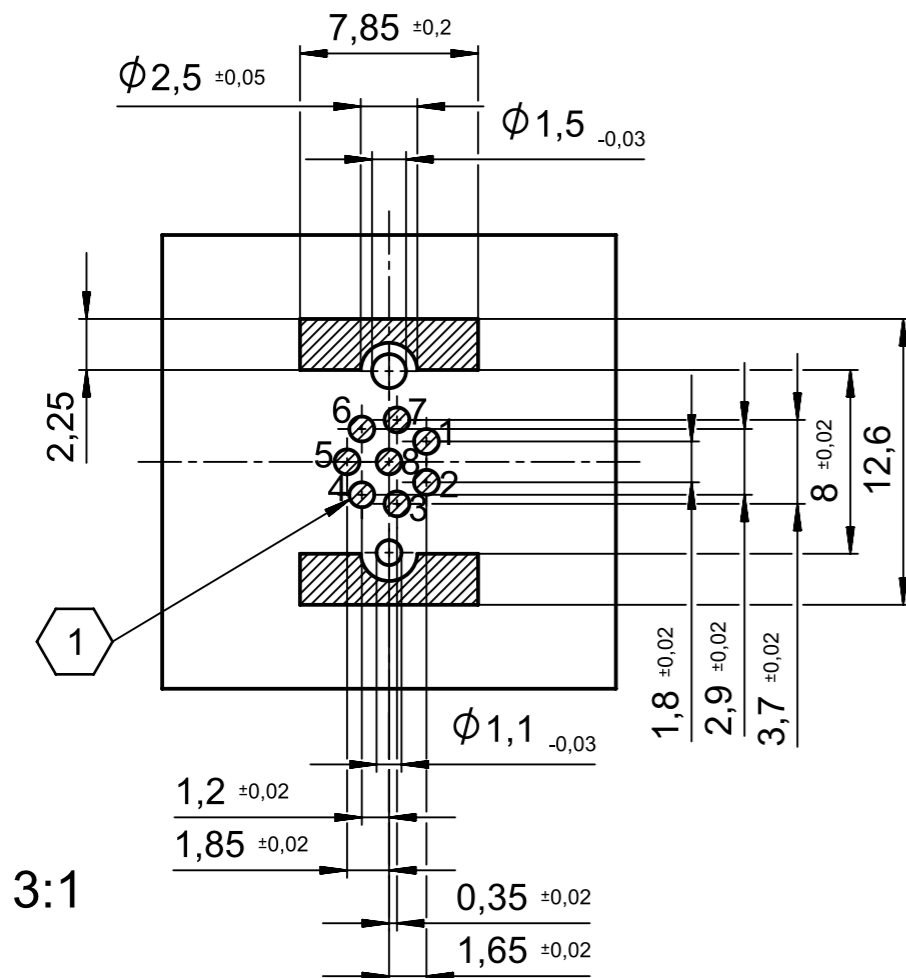
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socket face female



PCB-layout
(advice)



Coplanarity of all contacts and anchor plate \square 0.1

Recommended solder paste thickness 150µm

Further information on soldering process and recommended layout, see brochure "Connectors for SMT production"

- EN ISO 291 23/50

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